

Title (en)
SOLVENT-FREE HOT MELT ADHESIVE, ITS USE IN BONDING A POLAR LEATHER LAYER TO A NON-POLAR SUBSTRATE, AND LEATHER ARTICLES SO PRODUCED

Title (de)
LÖSUNGSMITTELFREIER SCHMELZKLEBSTOFF, DESSEN VERWENDUNG ZUR VERKLEBUNG EINER POLAREN LEDERSCHICHT AUF EINEM NICHTPOLAREN SUBSTRAT SOWIE SO HERGESTELLTE LEDERARTIKEL

Title (fr)
ADHESIF THERMOFUSIBLE SANS SOLVANT, SON UTILISATION POUR FIXER UNE COUCHE DE CUIR POLAIRE SUR UN SUBSTRAT NON POLAIRE, ET ARTICLES EN CUIR PRODUITS AU MOYEN DUDIT ADHESIF

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Application
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• EP 02016728 A 20020726

Abstract (en)
[origin: EP1384768A1] A solvent free, hot melt adhesive composition to be used for bonding a polar leather layer to a non-polar substrate, comprising: (a) a block copolymer, comprising at least one acid functionalized, selectively hydrogenated inner block predominantly derived from a conjugated diene which block has been functionalized by acid grafting, and at least two terminal blocks, predominantly derived from a vinylarene; (b) a hydrogenated hydrocarbon tackifying resin, with a softening point lower than 140 DEG C. in a weight proportion of 30 to 150 PHR (parts by weight of tackifying resin per 100 parts per weight of block copolymer); (c) a resin which is compatible with the predominantly poly(vinylarene) blocks, having a softening point lower than 140 DEG C in a weight proportion of from 10 to 80 PHR; (d) optionally a melt flow improving poly(alkylene) resin, which has been functionalized, in a weight proportion of from 0 to 30 parts PHR, and (e) stabilizers and/or additional auxiliaries in a weight proportion of from 0.1 to 1 PHR, as well as its use for bonding a polar leather layer to a non-polar substrate and formed leather articles composed by means of said adhesive composition.

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IPC 8 full level
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